SOT1092-2(DD)

plastic thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 36 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

14 March 2018 **Package information**

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN36
Package type industry code	HVQFN36
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	9-1-2018
Manufacturer package code	98ASA01179D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	6	-	mm
E	package width		-	-	6	-	mm
A	seated height		-	-	0.85	-	mm
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	36	-	A/A

2. Package outline

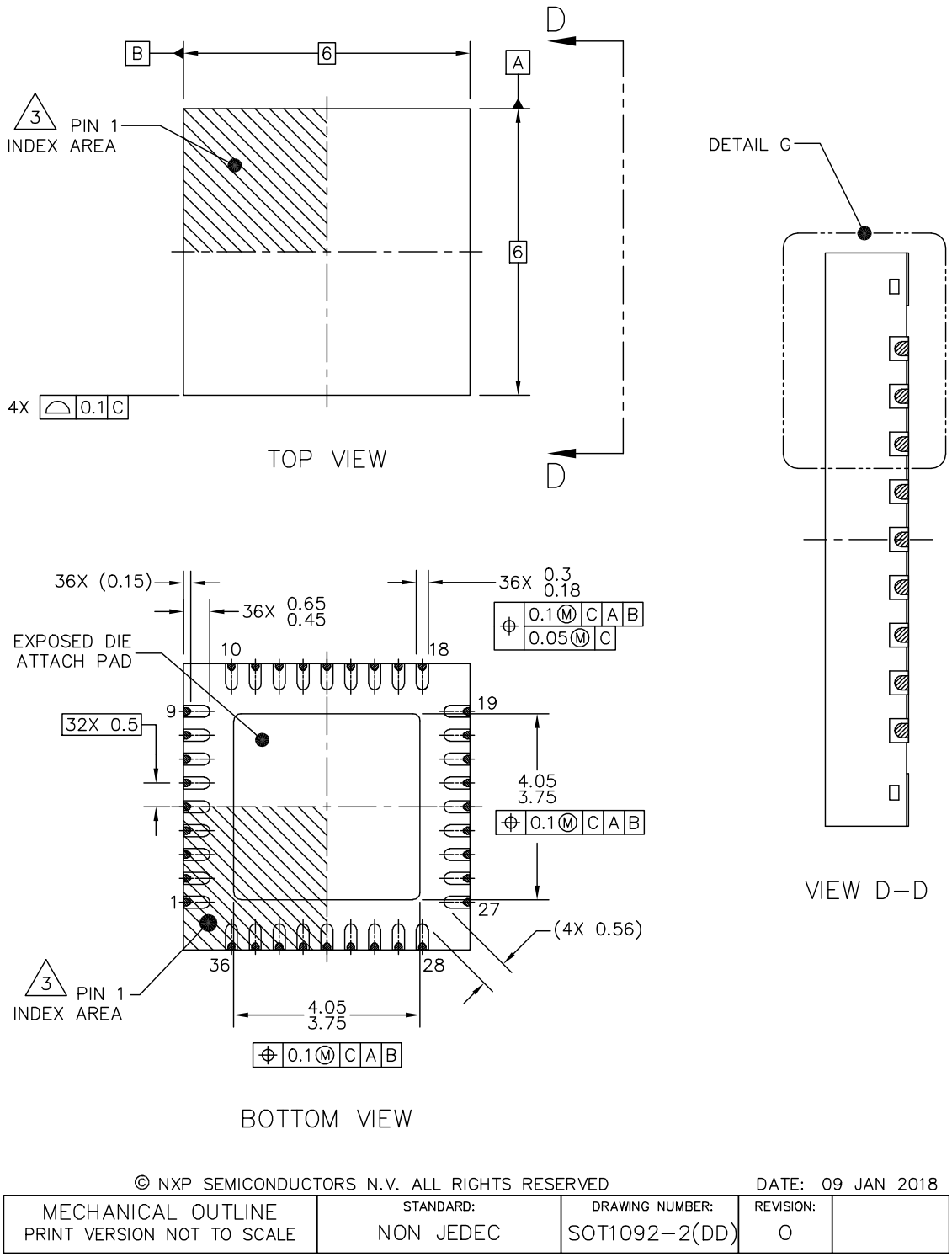
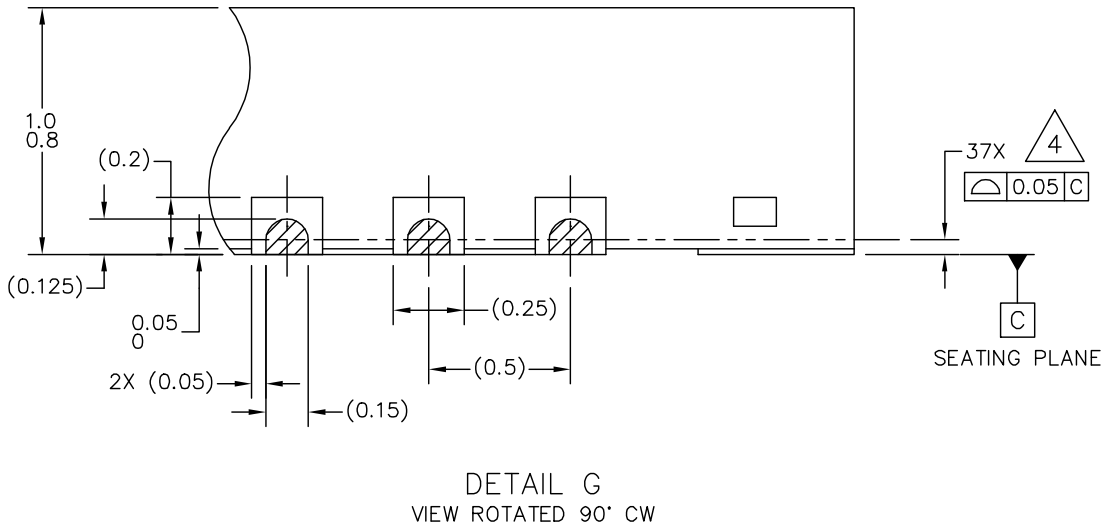


Fig. 1. Package outline HVQFN36 (SOT1092-2(DD))



DETAIL G
VIEW ROTATED 90° CW

DATE: 09 JAN 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1092-2(DD)	REVISION: O	

Fig. 2. Package outline dt HVQFN36 (SOT1092-2(DD))

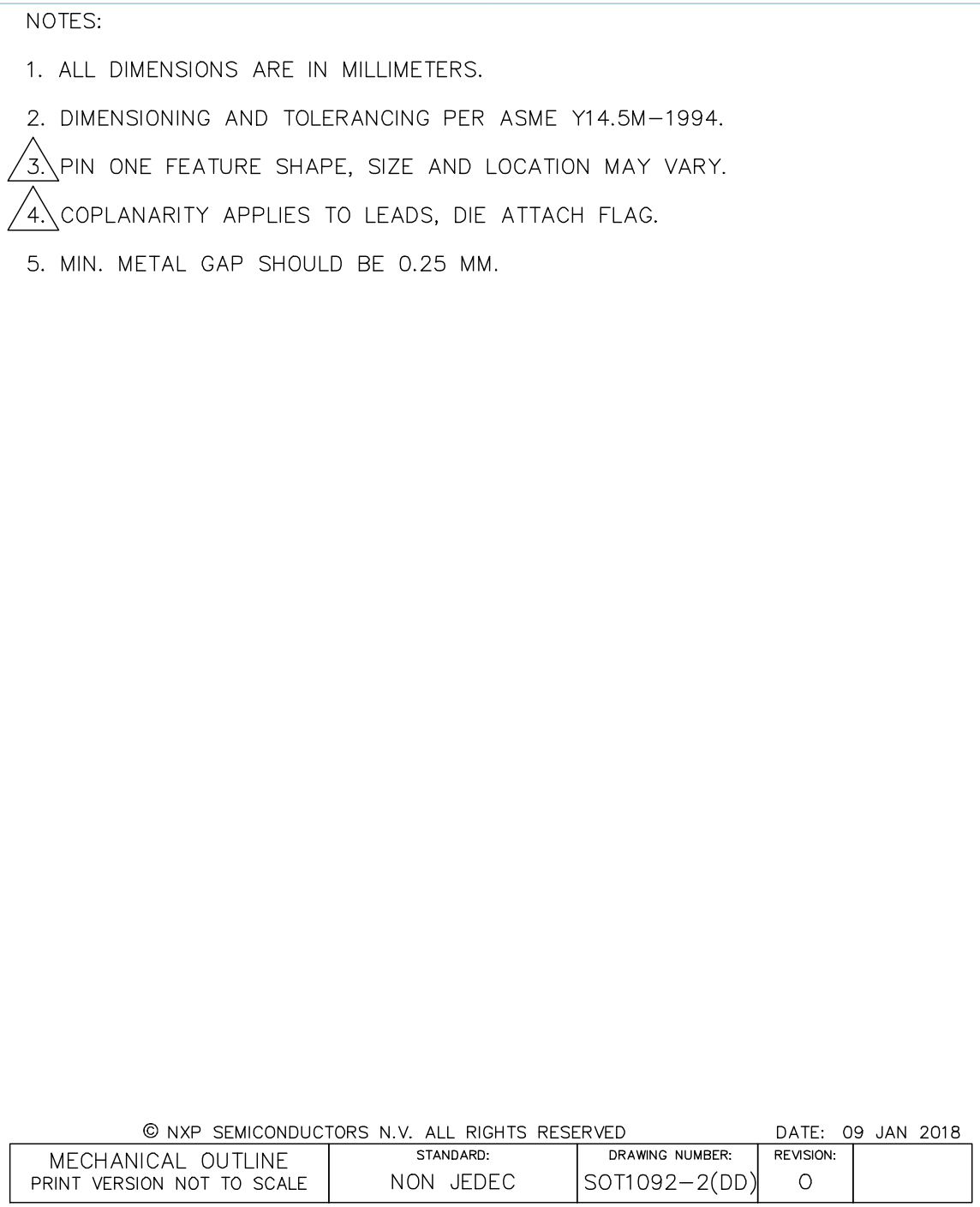


Fig. 3. Package outline note HVQFN36 (SOT1092-2(DD))

3. Soldering

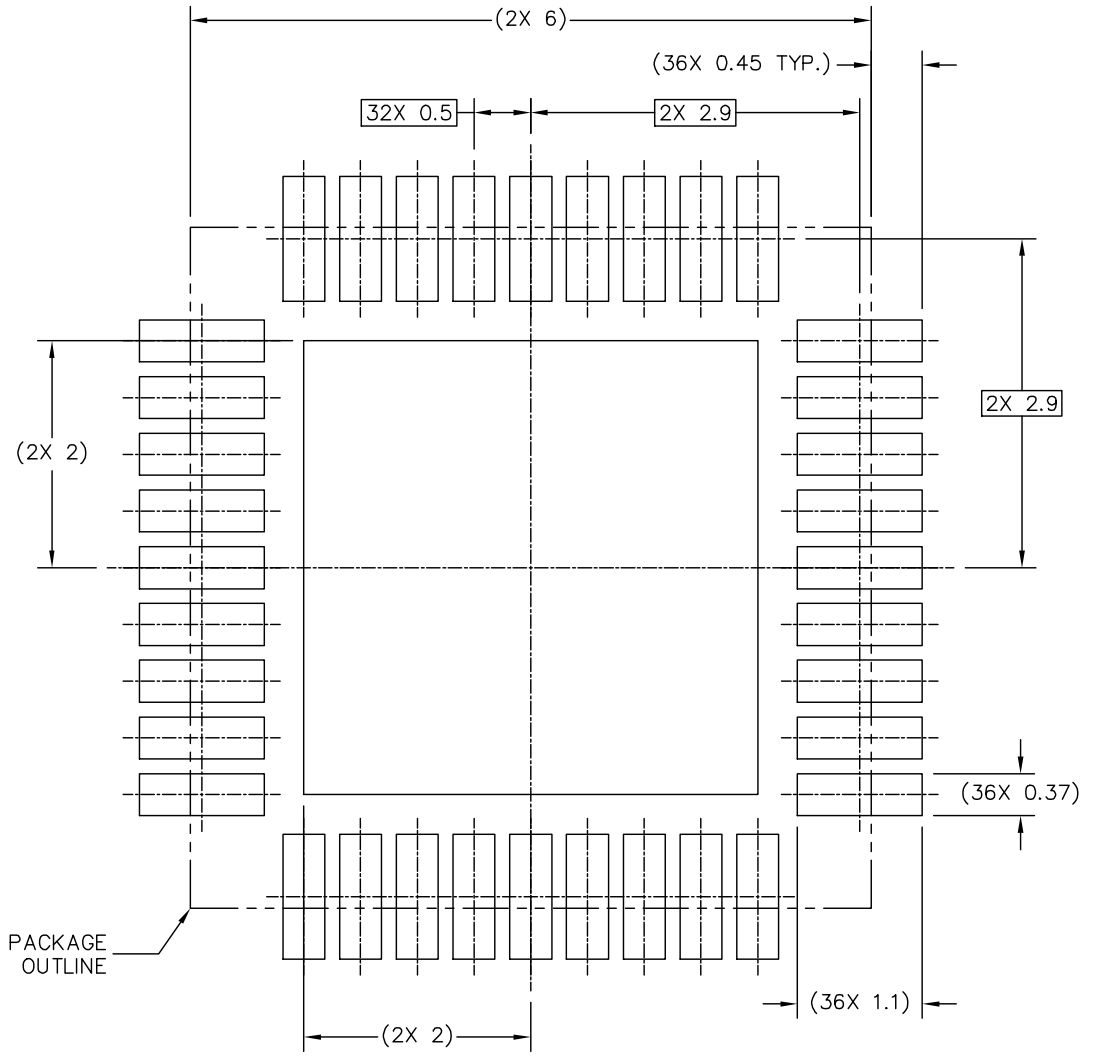
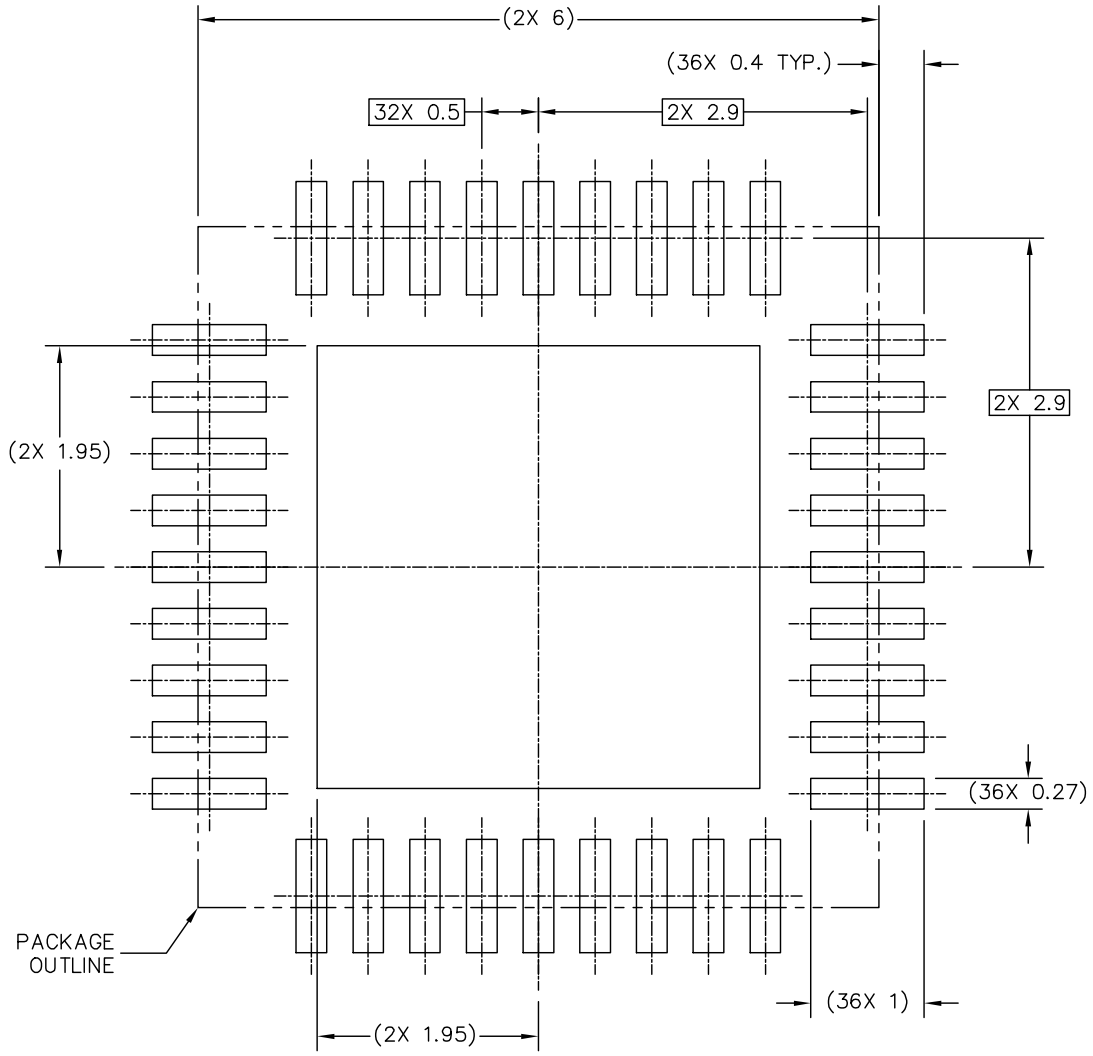


Fig. 4. Reflow soldering footprint for HVQFN36 (SOT1092-2(DD))



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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DATE: 09 JAN 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1092-2(DD)	REVISION: 0	

Fig. 5. Reflow soldering footprint part2 for HVQFN36 (SOT1092-2(DD))

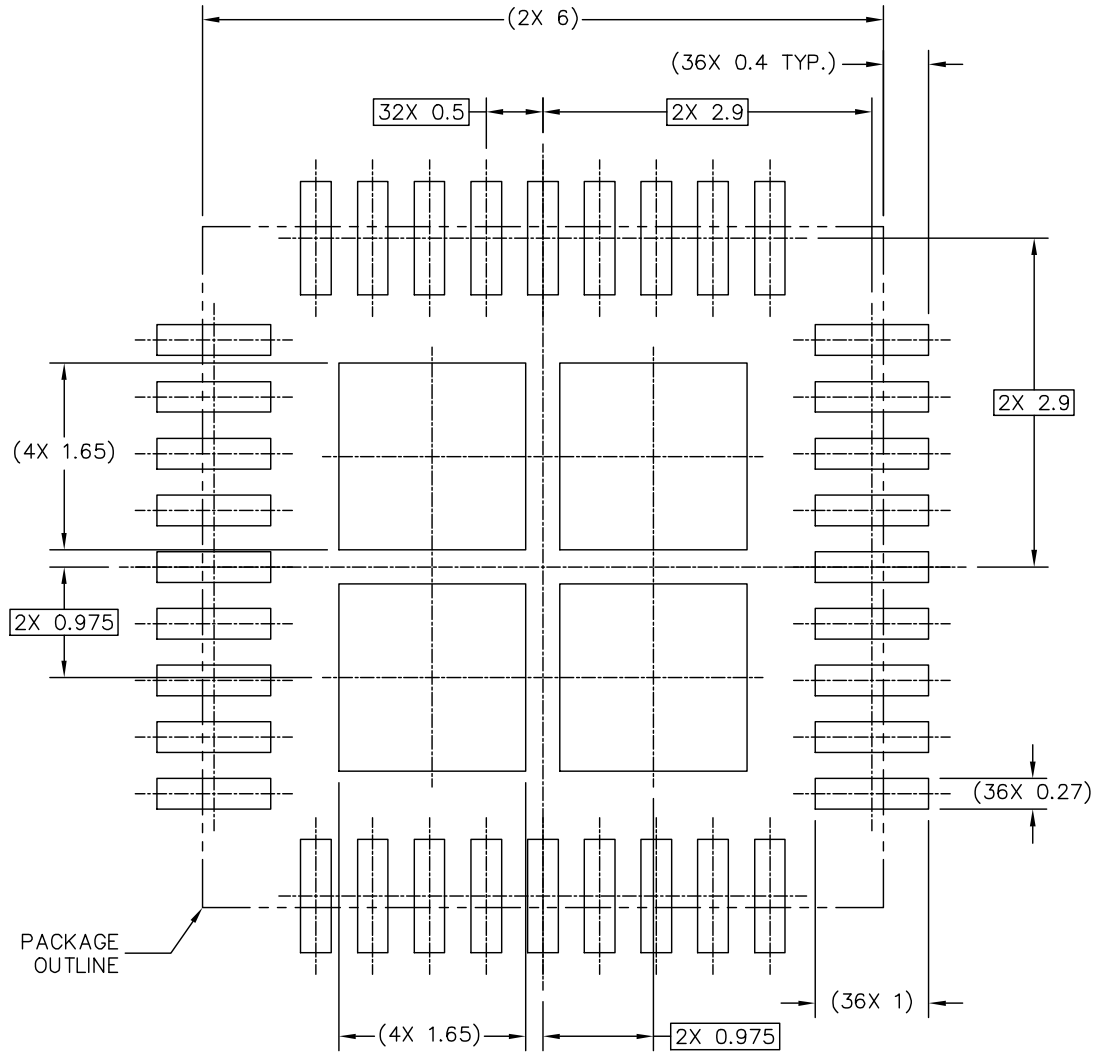

Fig. 6. Reflow soldering footprint part3 for HVQFN36 (SOT1092-2(DD))

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5. Contents

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